Preferred Device

Dual Series Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage -0.35 V (Typ) @ $I_F = 10 \text{ mAdc}$
- Pb-Free Package is Available

MAXIMUM RATINGS (T_J = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V _R	30	V
Forward Power Dissipation @ T _A = 25°C Derate above 25°C	P _F	225 1.8	mW mW/°C
Forward Current (DC)	IF	200 Max	mA
Junction Temperature	TJ	-55 to 125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

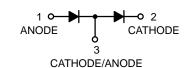
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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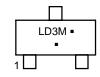
30 VOLT DUAL HOT-CARRIER DETECTOR AND SWITCHING DIODES



MARKING DIAGRAM



SOT-23 CASE 318 STYLE 11



LD3 = Device Code M = Date Code* ■ Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

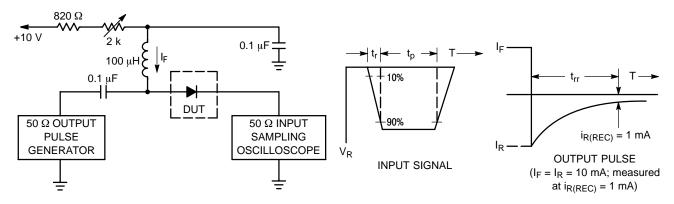
Device	Package	Shipping [†]
BAT54SLT1	SOT-23	3000 / Tape & Reel
BAT54SLT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

$\textbf{ELECTRICAL CHARACTERISTICS} \; (T_A = 25^{\circ}C \; \text{unless otherwise noted}) \; (\text{EACH DIODE})$

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \mu A$)	V _{(BR)R}	30	-	-	V
Total Capacitance (V _R = 1.0 V, f = 1.0 MHz)	C _T	_	7.6	10	pF
Reverse Leakage (V _R = 25 V)	I _R	_	0.5	2.0	μAdc
Forward Voltage (I _F = 0.1 mAdc)	V _F	_	0.22	0.24	Vdc
Forward Voltage (I _F = 30 mAdc)	V _F	_	0.41	0.5	Vdc
Forward Voltage (I _F = 100 mAdc)	V _F	_	0.52	0.8	Vdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}, Figure 1)$	t _{rr}	-	_	5.0	ns
Forward Voltage (I _F = 1.0 mAdc)	V _F	-	0.29	0.32	Vdc
Forward Voltage (I _F = 10 mAdc)	V _F	-	0.35	0.40	Vdc
Forward Current (DC)	I _F	-	-	200	mAdc
Repetitive Peak Forward Current	I _{FRM}	-	-	300	mAdc
Non-Repetitive Peak Forward Current (t < 1.0 s)	I _{FSM}	_	-	600	mAdc



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

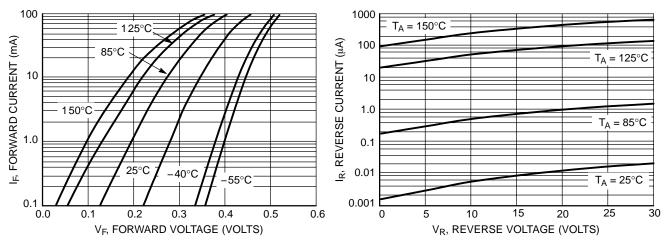


Figure 2. Forward Voltage

Figure 3. Leakage Current

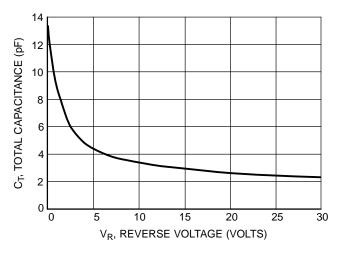
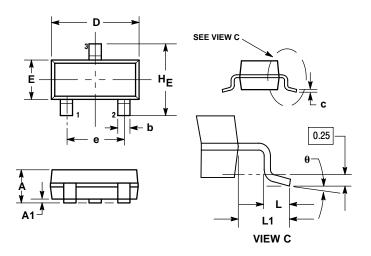


Figure 4. Total Capacitance

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



NOTES:

- NOTES.

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF DARK MATTERIAL. BASE MATERIAL. 318–01 THRU –07 AND –09 OBSOLETE, NEW
- STANDARD 318-08

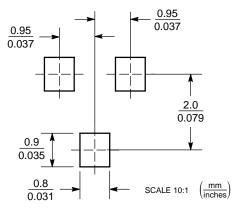
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 11:

- PIN 1. ANODE

 - 2. CATHODE 3. CATHODE-ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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